



## P-Channel 30 V (D-S) MOSFET

### PRODUCT SUMMARY

| $V_{DS}$ (V) | $R_{DS(on)}$ ( $\Omega$ )   | $I_D$ (A) <sup>d</sup> | $Q_g$ (Typ.) |
|--------------|-----------------------------|------------------------|--------------|
| -30          | 0.0033 at $V_{GS} = -10$ V  | -36                    | 90 nC        |
|              | 0.0046 at $V_{GS} = -4.5$ V | -29                    |              |

### FEATURES

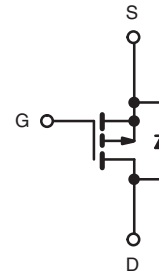
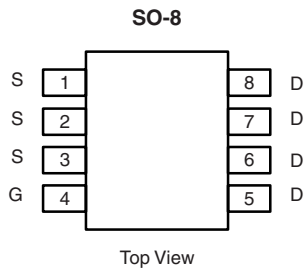
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET<sup>®</sup> Power MOSFET
- 100 %  $R_g$  Tested
- 100 % UIS Tested
- Compliant to RoHS Directive 2002/95/EC



RoHS  
COMPLIANT  
HALOGEN  
FREE

### APPLICATIONS

- Adaptor Switch
- High Current Load Switch
- Notebook



Ordering Information: Si4497DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

P-Channel MOSFET

### ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted

| Parameter  | Symbol         | Limit         | Unit |
|--|----------------|---------------|------|
| Drain-Source Voltage                             | $V_{DS}$       | -30           | V    |
| Gate-Source Voltage                              | $V_{GS}$       | $\pm 20$      |      |
| Continuous Drain Current ( $T_J = 150$ °C)       | $I_D$          | $T_C = 25$ °C | A    |
|  |                | $T_C = 70$ °C |      |
|  |                | $T_A = 25$ °C |      |
|  |                | $T_A = 70$ °C |      |
| Pulsed Drain Current                             | $I_{DM}$       | -70           | A    |
| Continuous Source-Drain Diode Current            | $I_S$          | $T_C = 25$ °C |      |
|  |                | $T_A = 25$ °C |      |
| Avalanche Current                                | $I_{AS}$       | -30           | mJ   |
| Single-Pulse Avalanche Energy                    | $E_{AS}$       | 45            |      |
| Maximum Power Dissipation                        | $P_D$          | $T_C = 25$ °C | W    |
|  |                | $T_C = 70$ °C |      |
|  |                | $T_A = 25$ °C |      |
|  |                | $T_A = 70$ °C |      |
| Operating Junction and Storage Temperature Range | $T_J, T_{stg}$ | -55 to 150    | °C   |

### THERMAL RESISTANCE RATINGS

| Parameter                                   | Symbol     | Typical | Maximum | Unit |
|---|------------|---------|---------|------|
| Maximum Junction-to-Ambient <sup>a, c</sup> | $R_{thJA}$ | 29      | 35      | °C/W |
| Maximum Junction-to-Foot                    | $R_{thJF}$ | 13      | 16      |      |

#### Notes:

- Surface mounted on 1" x 1" FR4 board.
- $t = 10$  s.
- Maximum under Steady State conditions is 80 °C/W.
- Based on  $T_C = 25$  °C.

| SPECIFICATIONS $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted |                         |   |      |        |           |                      |
|--|-------------------------|---|------|--------|-----------|----------------------|
| Parameter  | Symbol                  | Test Conditions   | Min. | Typ.   | Max.      | Unit                 |
| <b>Static</b>  |                         |   |      |        |           |                      |
| Drain-Source Breakdown Voltage   | $V_{DS}$                | $V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$  | -30  |        |           | V                    |
| $V_{DS}$ Temperature Coefficient   | $\Delta V_{DS}/T_J$     | $I_D = -250\text{ }\mu\text{A}$   |      | -26    |           | mV/ $^\circ\text{C}$ |
| $V_{GS(th)}$ Temperature Coefficient                                     | $\Delta V_{GS(th)}/T_J$ |   | 5.5  |        |           |                      |
| Gate-Source Threshold Voltage  | $V_{GS(th)}$            | $V_{DS} = V_{GS}, I_D = -250\text{ }\mu\text{A}$  | -1.0 |        | -2.5      | V                    |
| Gate-Source Leakage  | $I_{GSS}$               | $V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$   |      |        | $\pm 100$ | nA                   |
| Zero Gate Voltage Drain Current  | $I_{DSS}$               | $V_{DS} = -30\text{ V}, V_{GS} = 0\text{ V}$  |      |        | -1        | $\mu\text{A}$        |
|  |                         | $V_{DS} = -30\text{ V}, V_{GS} = 0\text{ V}, T_J = 55\text{ }^\circ\text{C}$  |      |        | -5        |                      |
| On-State Drain Current <sup>a</sup>                                      | $I_{D(on)}$             | $V_{DS} \geq -10\text{ V}, V_{GS} = -10\text{ V}$   | -30  |        |           | A                    |
| Drain-Source On-State Resistance <sup>a</sup>                            | $R_{DS(on)}$            | $V_{GS} = -10\text{ V}, I_D = -20\text{ A}$   |      | 0.0027 | 0.0033    | $\Omega$             |
|  |                         | $V_{GS} = -4.5\text{ V}, I_D = -15\text{ A}$  |      | 0.0038 | 0.0046    |                      |
| Forward Transconductance <sup>a</sup>                                    | $g_{fs}$                | $V_{DS} = -10\text{ V}, I_D = -20\text{ A}$   |      | 75     |           | S                    |
| <b>Dynamic<sup>b</sup></b>   |                         |   |      |        |           |                      |
| Input Capacitance  | $C_{iss}$               | $V_{DS} = -15\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$  |      | 9685   |           | pF                   |
| Output Capacitance   | $C_{oss}$               |   | 995  |        |           |                      |
| Reverse Transfer Capacitance   | $C_{rss}$               |   | 995  |        |           |                      |
| Total Gate Charge  | $Q_g$                   | $V_{DS} = -15\text{ V}, V_{GS} = -10\text{ V}, I_D = -20\text{ A}$  |      | 190    | 285       | nC                   |
|  |                         |   |      | 90     | 135       |                      |
| Gate-Source Charge   | $Q_{gs}$                | $V_{DS} = -15\text{ V}, V_{GS} = -4.5\text{ V}, I_D = -20\text{ A}$   |      | 27.5   |           |                      |
| Gate-Drain Charge  | $Q_{gd}$                |   |      | 26.5   |           |                      |
| Gate Resistance  | $R_g$                   | $f = 1\text{ MHz}$  | 0.5  | 2.3    | 4.6       | $\Omega$             |
| Turn-On Delay Time   | $t_{d(on)}$             | $V_{DD} = -15\text{ V}, R_L = 1.5\text{ }\Omega$<br>$I_D \equiv -10\text{ A}, V_{GEN} = -10\text{ V}, R_g = 1\text{ }\Omega$  |      | 19     | 35        | ns                   |
| Rise Time  | $t_r$                   |   |      | 13     | 25        |                      |
| Turn-Off Delay Time  | $t_{d(off)}$            |   |      | 115    | 200       |                      |
| Fall Time  | $t_f$                   |   |      | 25     | 50        |                      |
| Turn-On Delay Time   | $t_{d(on)}$             | $V_{DD} = -15\text{ V}, R_L = 1.5\text{ }\Omega$<br>$I_D \equiv -10\text{ A}, V_{GEN} = -4.5\text{ V}, R_g = 1\text{ }\Omega$ |      | 100    | 180       |                      |
| Rise Time  | $t_r$                   |   |      | 75     | 150       |                      |
| Turn-Off Delay Time  | $t_{d(off)}$            |   |      | 100    | 180       |                      |
| Fall Time  | $t_f$                   |   |      | 42     | 80        |                      |
| <b>Drain-Source Body Diode Characteristics</b>                           |                         |   |      |        |           |                      |
| Continuous Source-Drain Diode Current                                    | $I_S$                   | $T_C = 25\text{ }^\circ\text{C}$  |      |        | -36       | A                    |
| Pulse Diode Forward Current  | $I_{SM}$                |   |      |        | -70       |                      |
| Body Diode Voltage   | $V_{SD}$                | $I_S = -3\text{ A}, V_{GS} = 0\text{ V}$  |      | -0.70  | -1.2      | V                    |
| Body Diode Reverse Recovery Time   | $t_{rr}$                | $I_F = -10\text{ A}, di/dt = 100\text{ A}/\mu\text{s}, T_J = 25\text{ }^\circ\text{C}$  |      | 31     | 60        | ns                   |
| Body Diode Reverse Recovery Charge                                       | $Q_{rr}$                |   |      | 23     | 45        | nC                   |
| Reverse Recovery Fall Time   | $t_a$                   |   |      | 13     |           | ns                   |
| Reverse Recovery Rise Time   | $t_b$                   |   |      | 18     |           |                      |

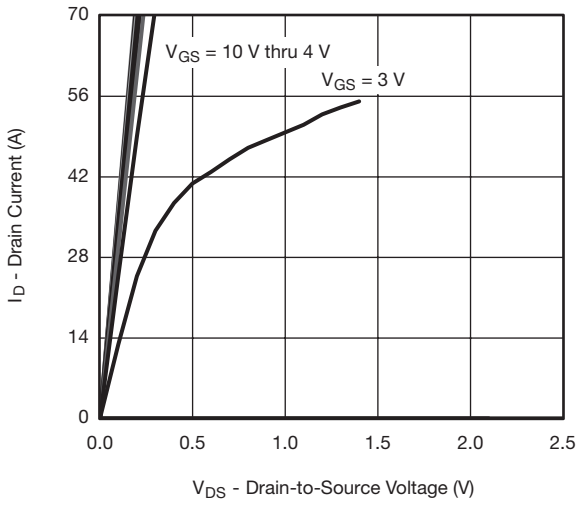
Notes:

- a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .  
b. Guaranteed by design, not subject to production testing.

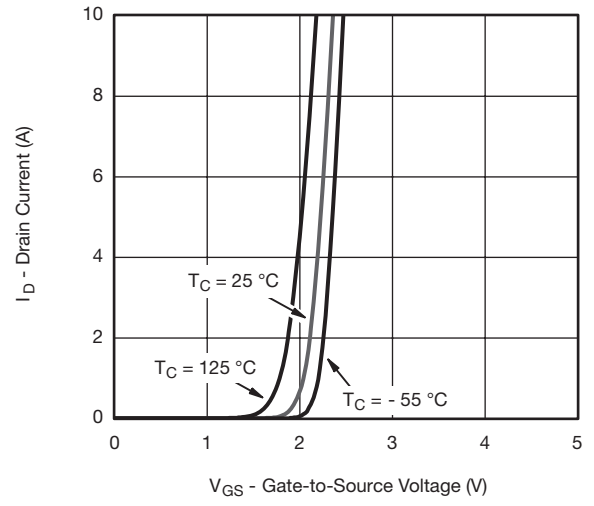
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



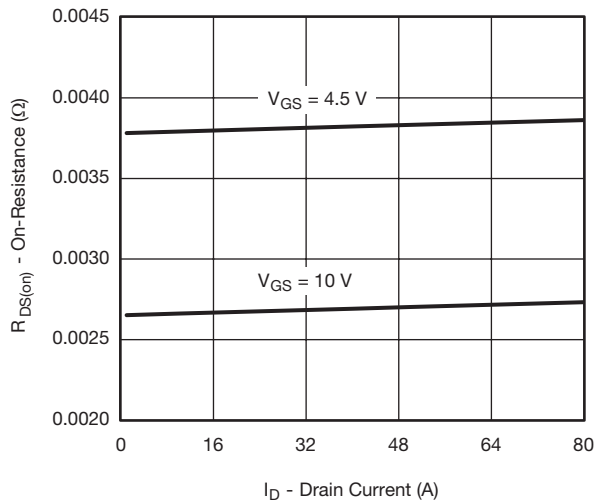
**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted



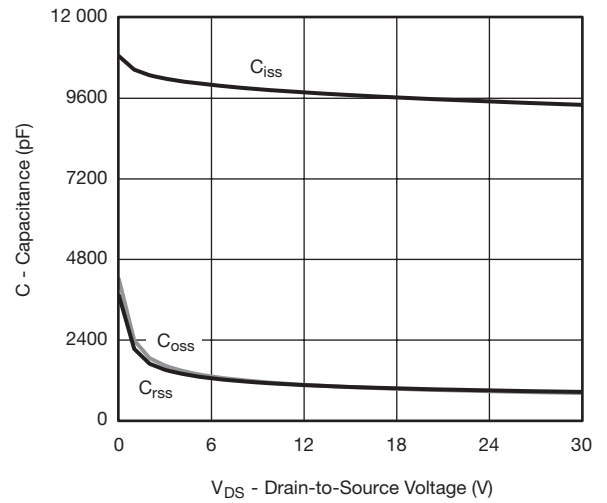
**Output Characteristics**



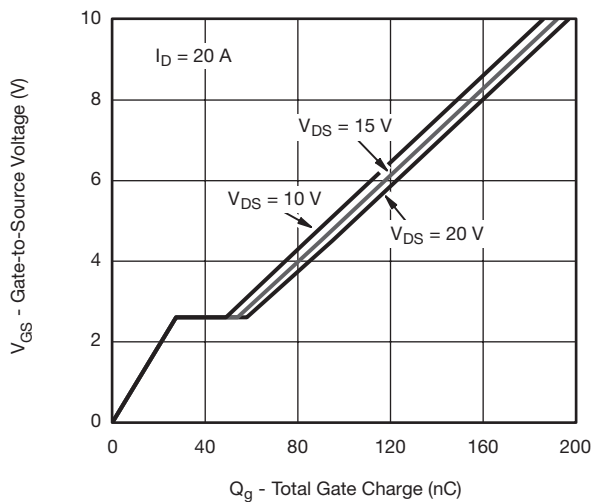
**Transfer Characteristics**



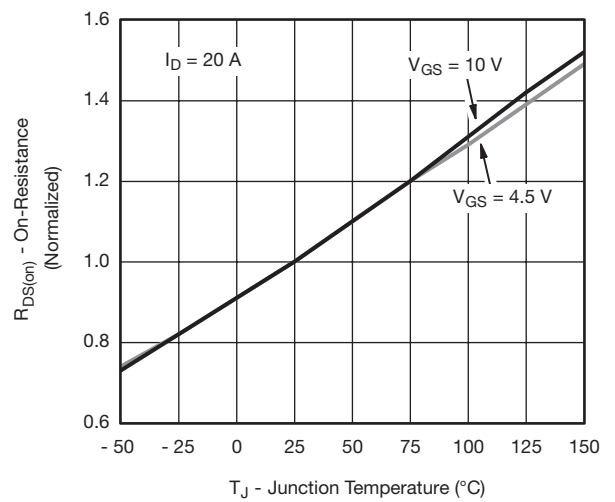
**On-Resistance vs. Drain Current**



**Capacitance**



**Gate Charge**



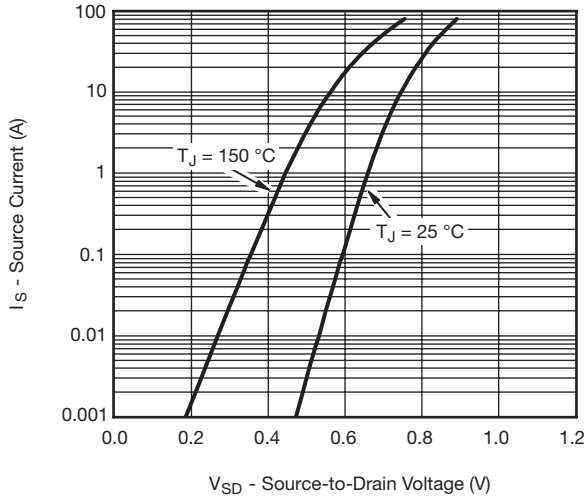
**On-Resistance vs. Junction Temperature**

# Si4497DY

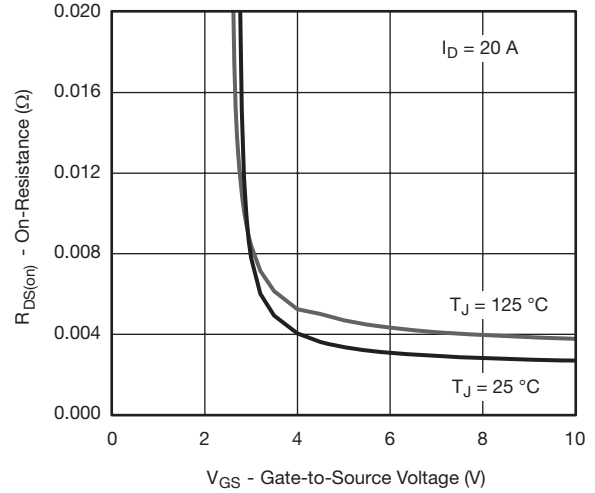
Vishay Siliconix



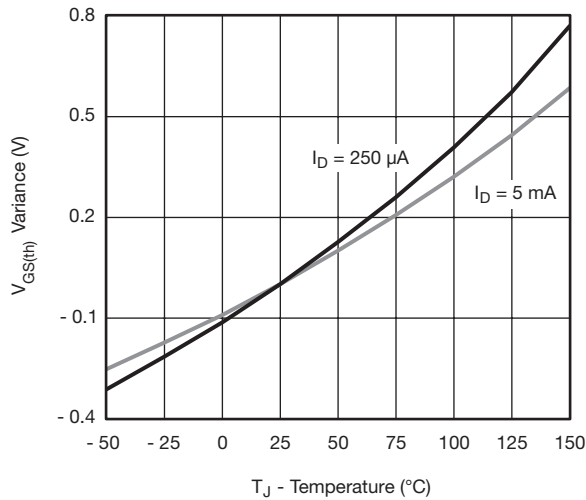
## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



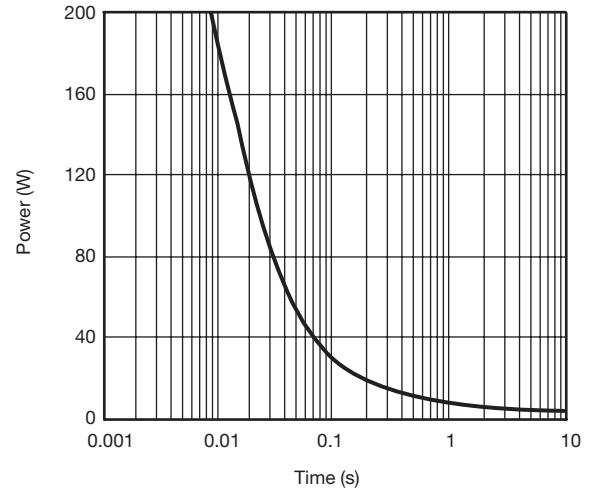
Source-Drain Diode Forward Voltage



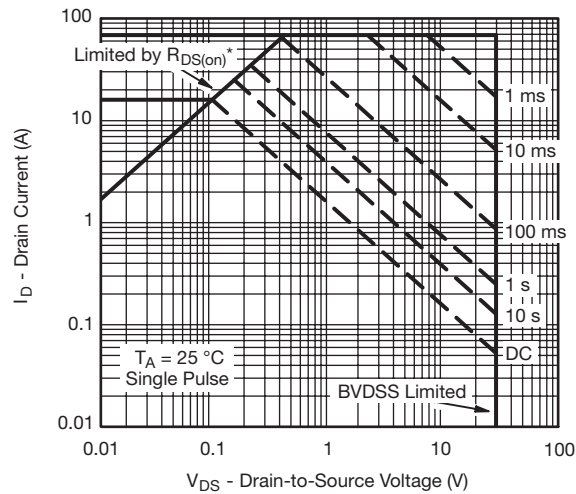
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power, Junction-to-Ambient

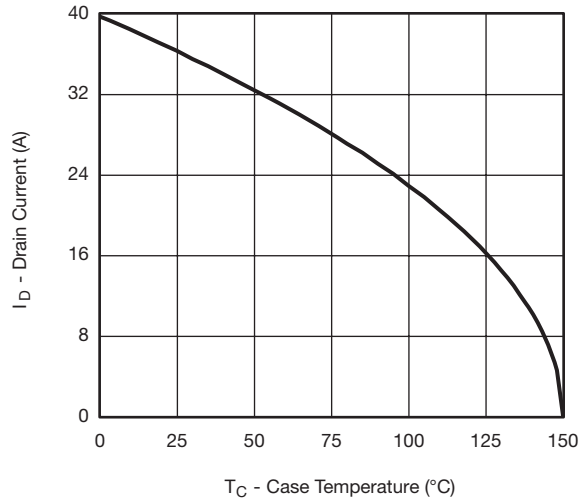


Safe Operating Area

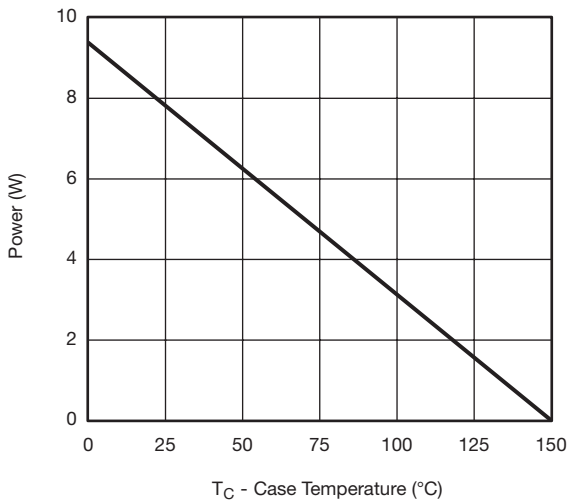
\*  $V_{GS} >$  minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified



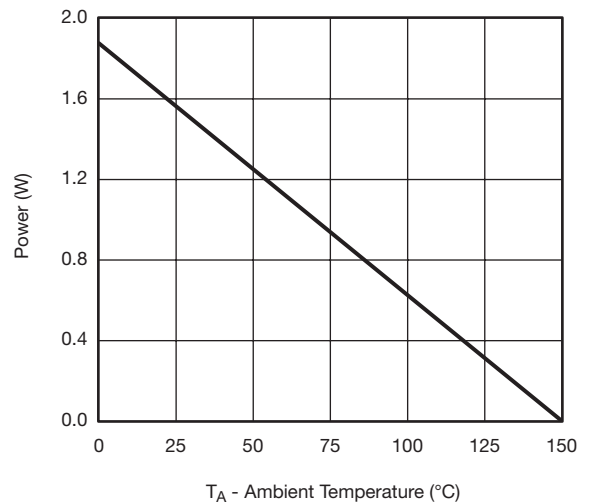
**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted



**Current Derating\***



**Power Derating, Junction-to-Foot**



**Power Derating, Junction-to-Ambient**

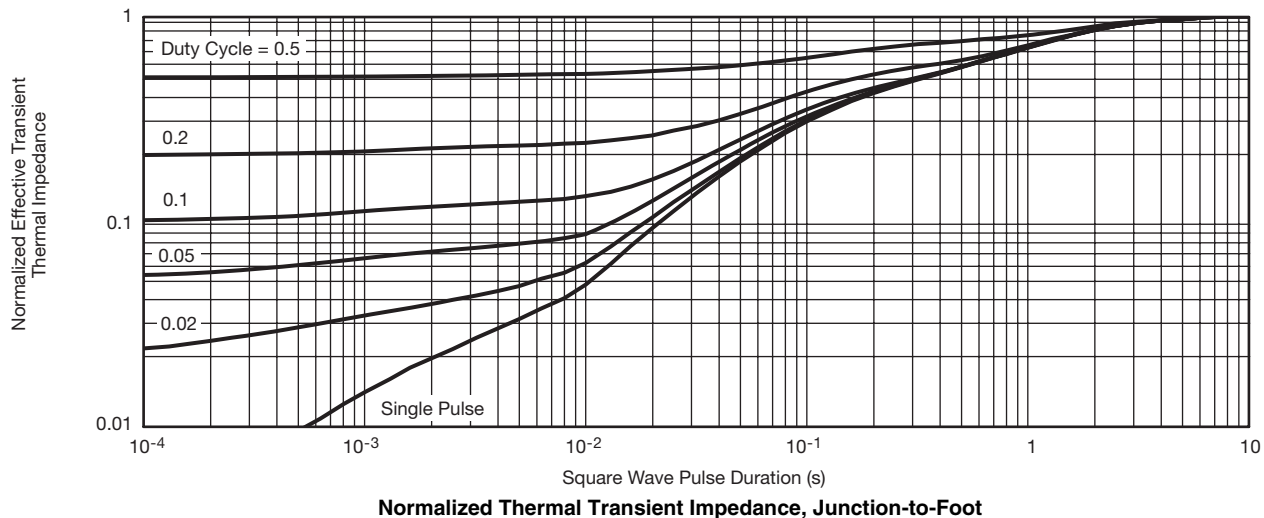
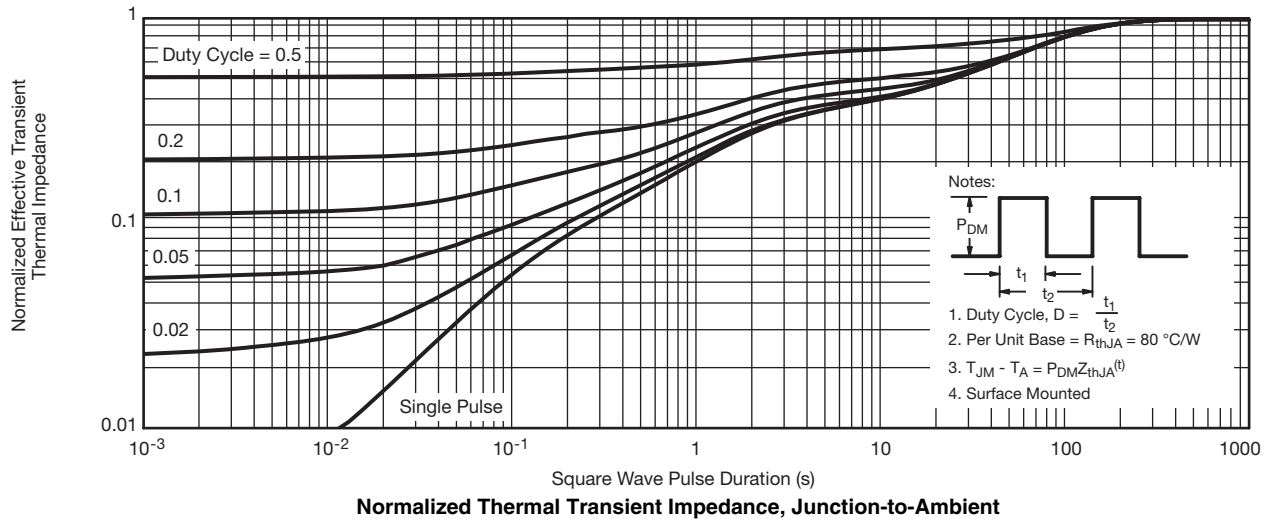
\* The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

# Si4497DY

Vishay Siliconix



## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see [www.vishay.com/ppg?65748](http://www.vishay.com/ppg?65748).

## SOIC (NARROW): 8-LEAD

JEDEC Part Number: MS-012



| DIM                            | MILLIMETERS |      | INCHES    |       |
|--------------------------------|-------------|------|-----------|-------|
|                                | Min         | Max  | Min       | Max   |
| A                              | 1.35        | 1.75 | 0.053     | 0.069 |
| A <sub>1</sub>                 | 0.10        | 0.20 | 0.004     | 0.008 |
| B                              | 0.35        | 0.51 | 0.014     | 0.020 |
| C                              | 0.19        | 0.25 | 0.0075    | 0.010 |
| D                              | 4.80        | 5.00 | 0.189     | 0.196 |
| E                              | 3.80        | 4.00 | 0.150     | 0.157 |
| e                              | 1.27 BSC    |      | 0.050 BSC |       |
| H                              | 5.80        | 6.20 | 0.228     | 0.244 |
| h                              | 0.25        | 0.50 | 0.010     | 0.020 |
| L                              | 0.50        | 0.93 | 0.020     | 0.037 |
| q                              | 0°          | 8°   | 0°        | 8°    |
| S                              | 0.44        | 0.64 | 0.018     | 0.026 |
| ECN: C-06527-Rev. I, 11-Sep-06 |             |      |           |       |
| DWG: 5498                      |             |      |           |       |

## RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads  
Dimensions in Inches/(mm)

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